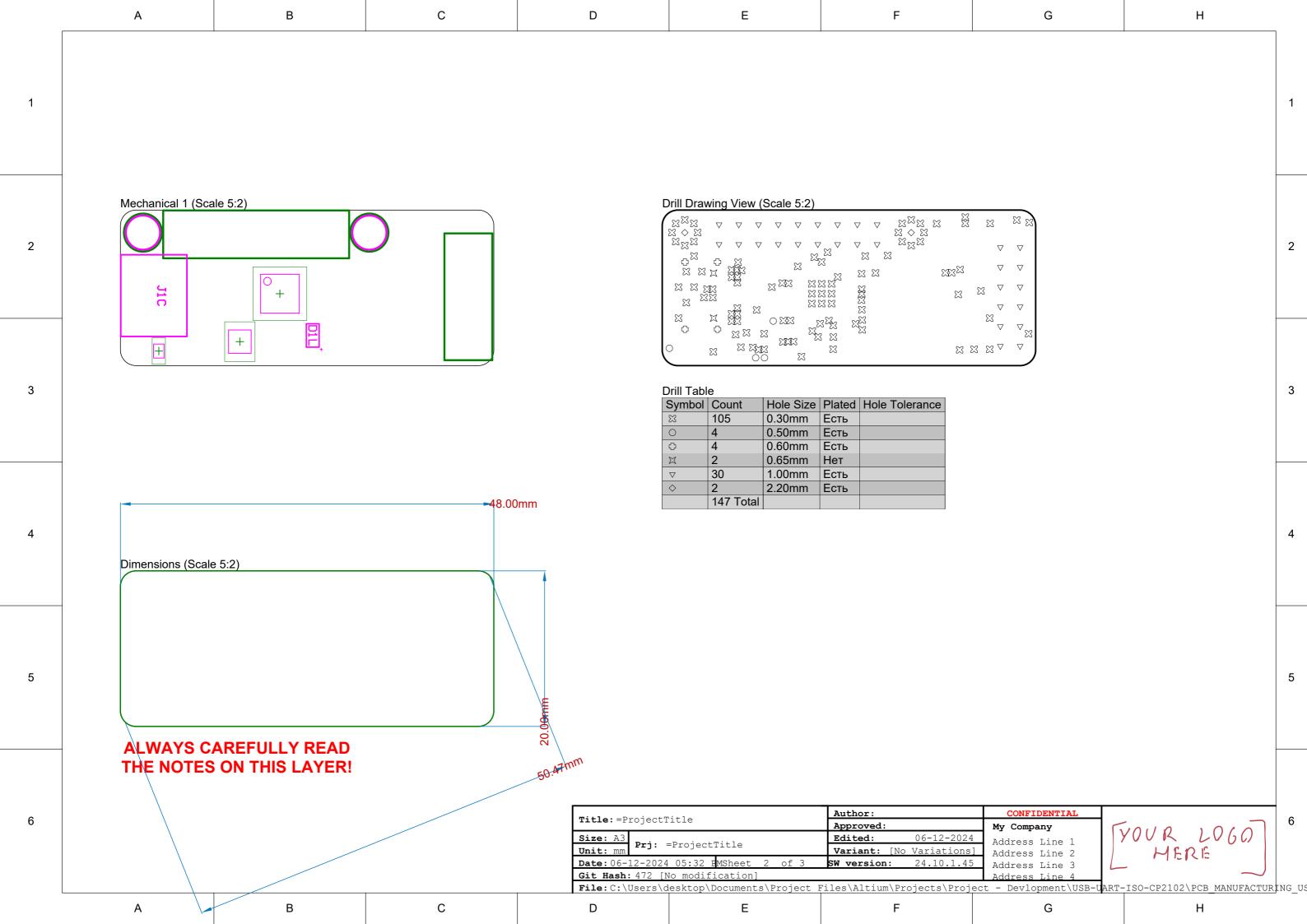
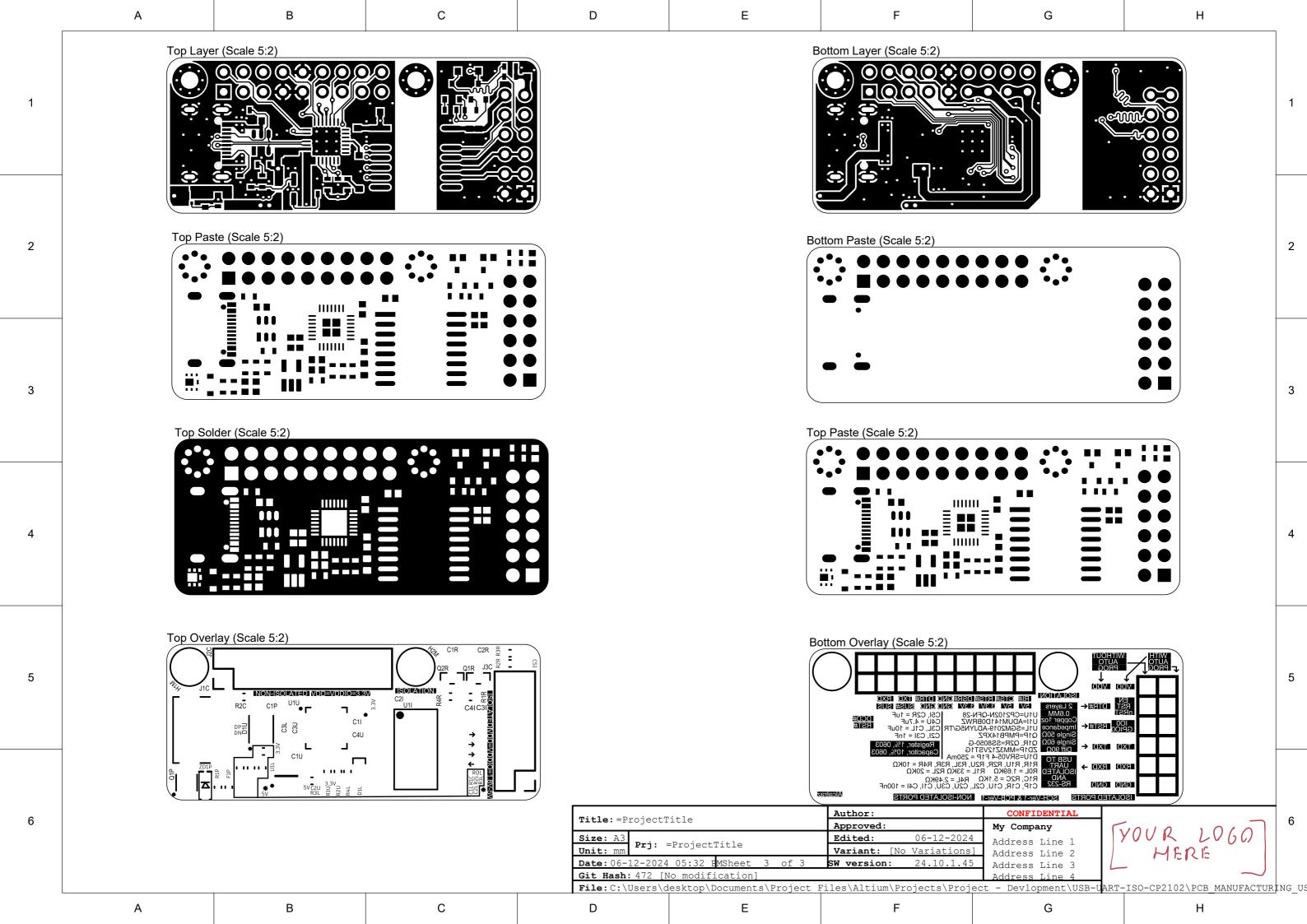
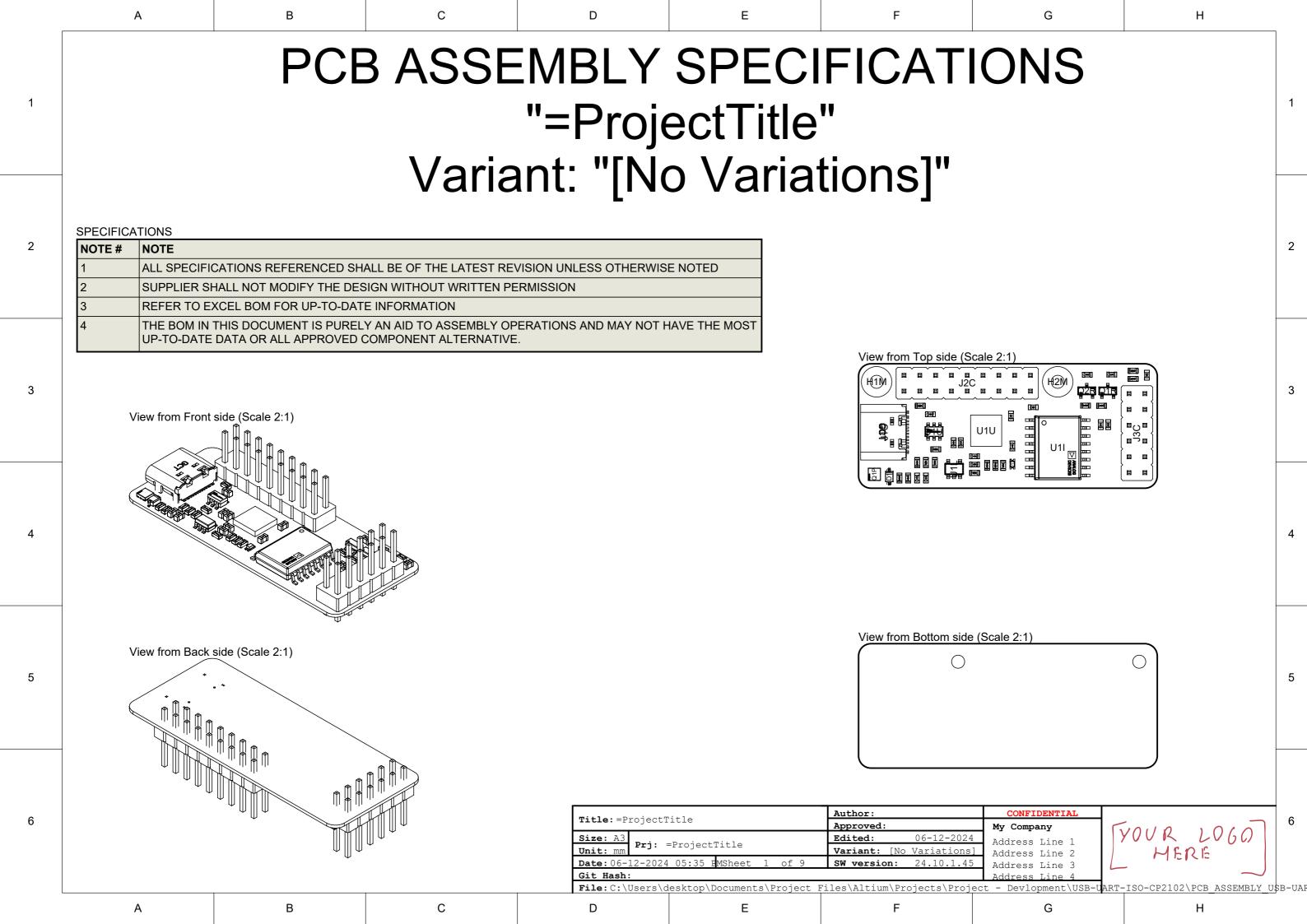
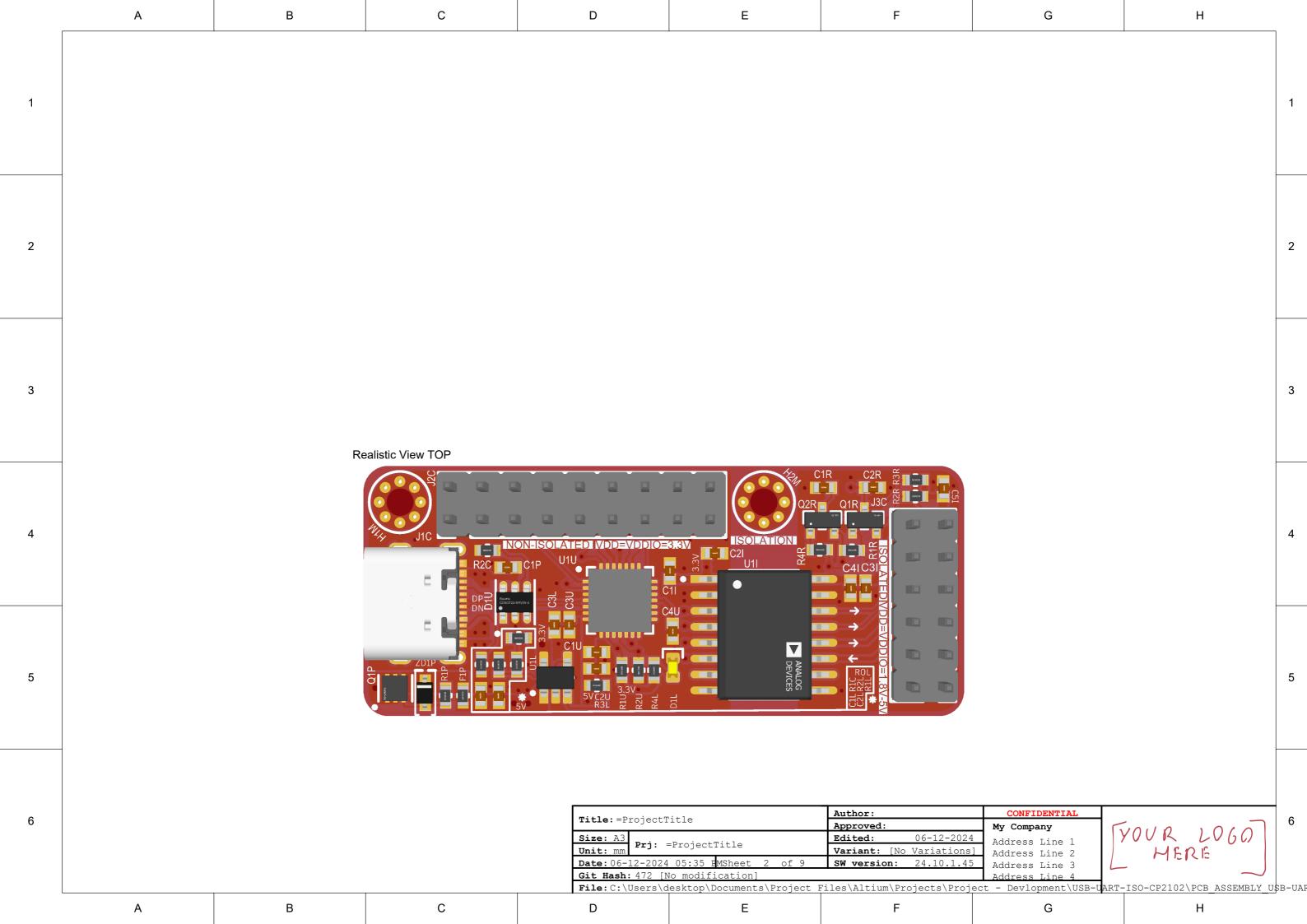


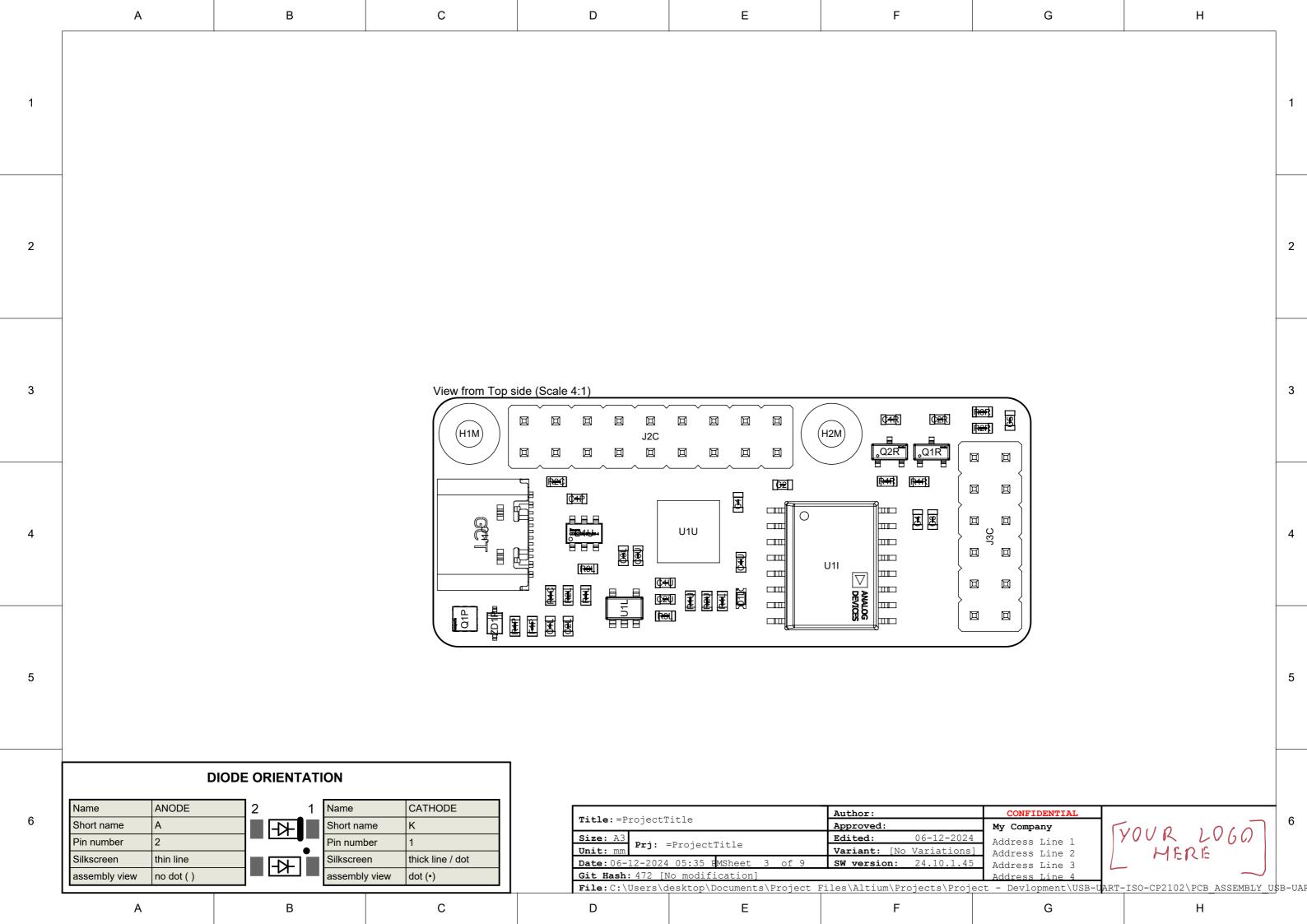
PCB MANUFACTURING SPECIFICATIONS "=ProjectTitle" **SPECIFICATIONS SPECIFICATIONS** NOTE# NOTE LENGHT 20.00mm **WIDTH** ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK 48.00mm **LAYERS** SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION FR-4 **MATERIAL** ALL MATERIALS SHALL BE RoHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN RoHS ASSEMBLY. RoHS LOGO SHALL BE MARKED IN SILKSCREEN INK BY THE SUPPLIER WHERE INDICATED BY **MATERIAL MIN TG** 130-140 THE TEXT "PLACE MARKINGS HERE" TRACK WIDTH/CLEARANCE 10 mils / 10 mils COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE **THICKNESS** 0.6mm FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS **COPPER THICKNESS** 35um (1oz) ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-YES, TOP AND BOTTOM SOLDERMASK CONDUCTIVE. PERMANENT INK. **GREEN SOLDERMASK COLOR** MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE SILKSCREEN YES. TOP AND BOTTOM RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM NOTES" BY THE TEXT "PLACE MARKINGS SILKSCREEN COLOR WHITE MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRESSION UNLESS SURFACE FINISH **HASL LEAD FREE** OTHERWISE NOTED ONTO THE LAYER "PCBM NOTES" NO **GOLD FINGERS** SUPPLIER SHALL CHECK PCBM NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS **CHAMFERING** YES MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES YES IMPEDANCE CONTROL HALF-CUT/CASTELLATED HOLES NO **BURIED/BLIND VIAS** NO NO VIAS FILLED WITH RESIN Layer Stack Legend Material Layer Thickness Dielectric Material Type Gerber NO **CARBON MASK** Top Overlay GTO COUNTERSINKS/COUNTERBORES NO Surface Material Top Solder Solder Mask GTS NO **Z-AXIS MILLING** Copper Top Layer Signal GTL PEELABLE SOLDERMASK NO Core 0.50mm FR-4 Dielectric **GBL** 0.04mm Signal Solder Mask GBS Surface Material Bottom Solder 0.02mm Solder Resist GBO **Bottom Overlay** Legend Total thickness: 0.60mm NON-COPPER LAYER THICKNESS FOR REFERENCE ONLY LAYERS OF TYPE "INTERNAL PLANE" ARE NEGATIVE Author: Title: =ProjectTitle Approved: My Company Prj: =ProjectTitle Address Line 1 Variant: Address Line 2 Date: 06-12-2024 SW version: Address Line 3 С G В

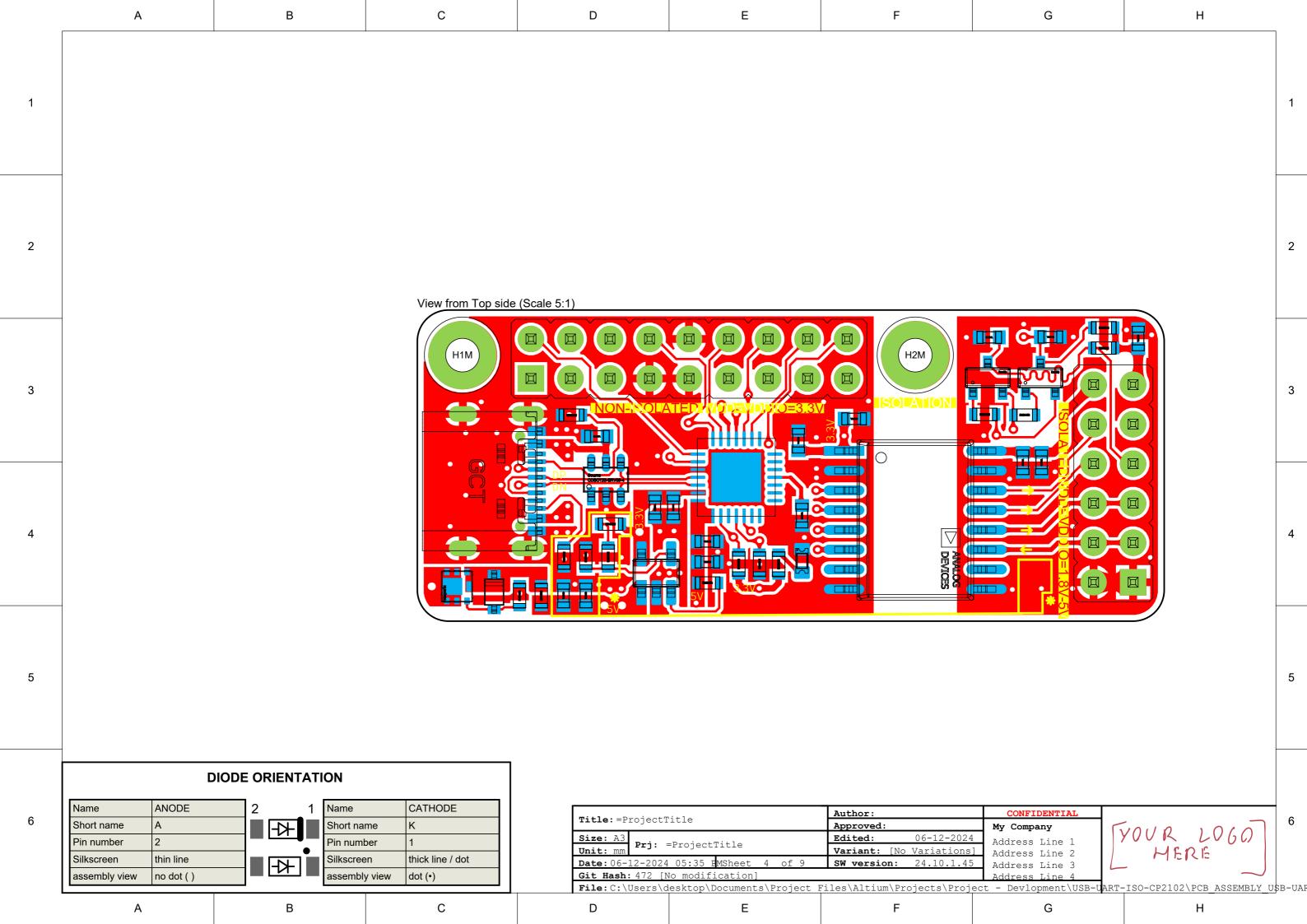


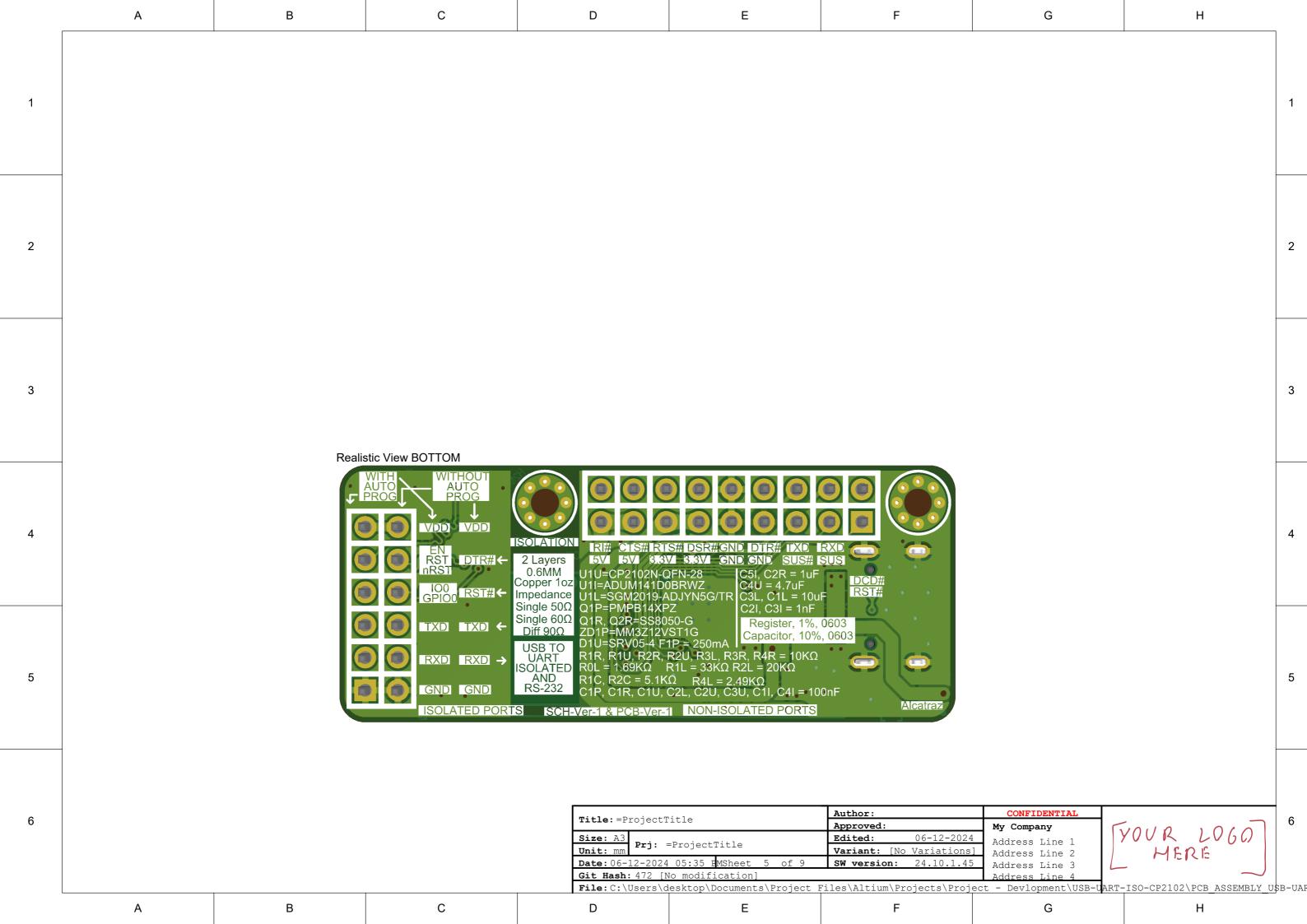


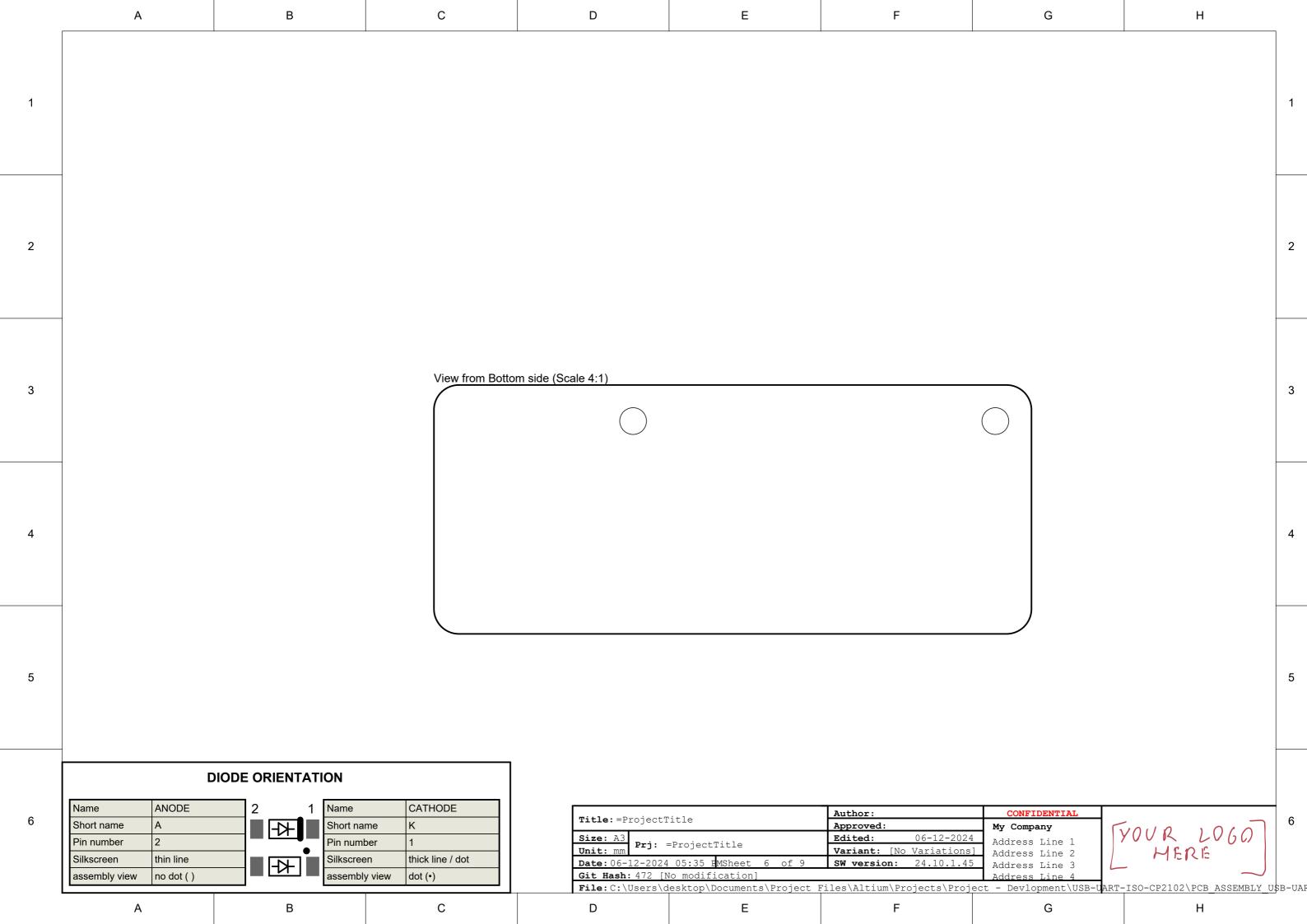


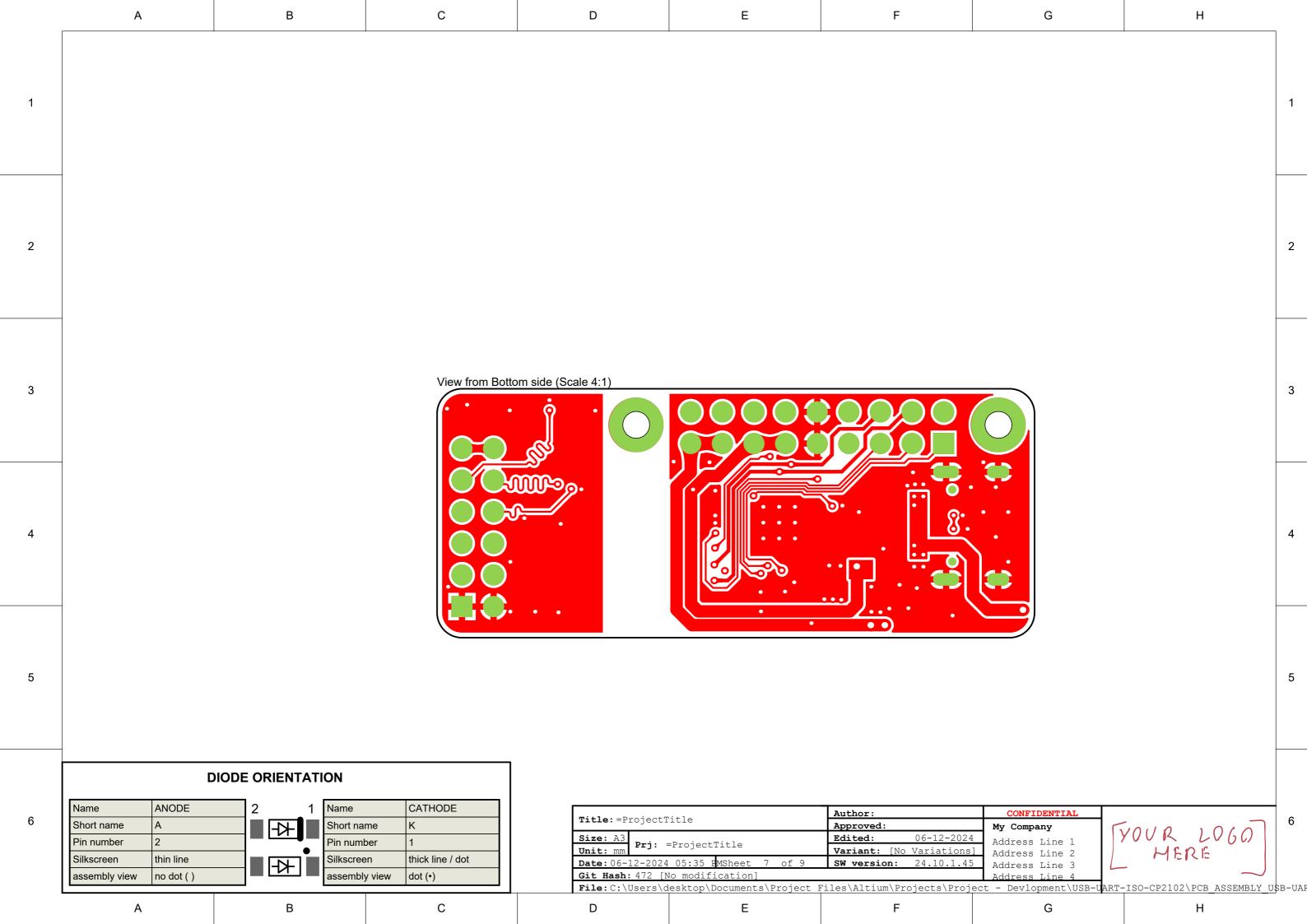


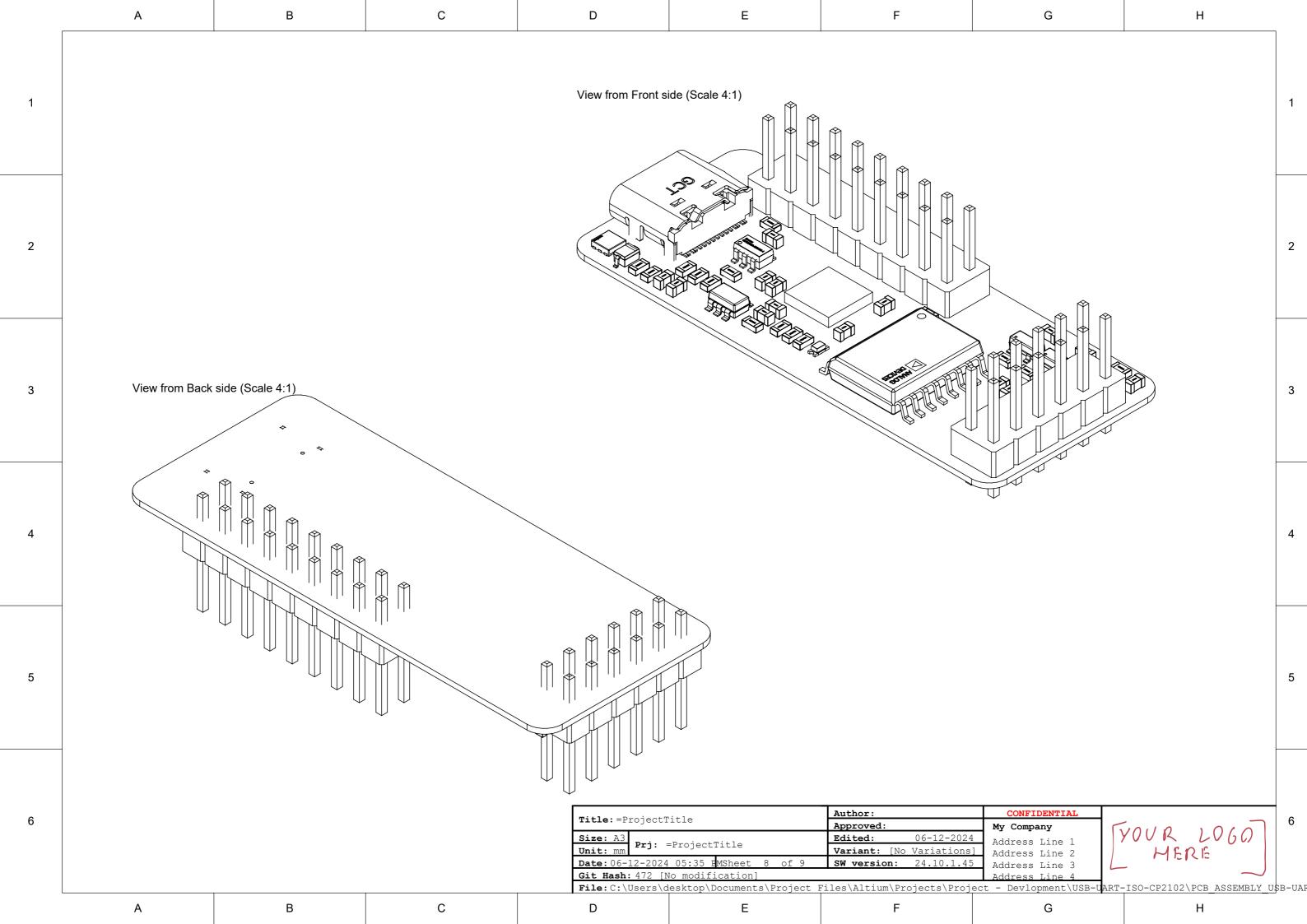












	А		В	С	D	E	F	G	Н	
1										1
2	Bill Of Materials Line # Description			Designator	Quantity	Manufacturer Part	Dort Number	Lover		
	Line #		Description Can Cer 0 1UF 6 3V X7	2 0603	Designator C1I, C1R, C3		Number 1 KGM15AR70J104KM	Part Number	Layer	2
		Multilayer C	Cap Cer 0.1UF 6.3V X7R 0603 Multilayer Ceramic Capacitor, 10 uF, 10 V, ± 10%, X5R, 0603 [1608 Metric]		C1L	1				
	Multilayer Ceramic Capacitor, 0.1 uF, 10 V, ± 10%, X7R, 0603 [1608 Metric]		C1P, C1U, C2L, C2	2U, C4I 5	C0603C104K8RAC786 7					
		Cap Ceramic 0.001uF 6.3V C0G 10% SMD 0603 125°C Paper T/R Ceramic Capacitor, Multilayer, Ceramic, 10V, 10% +Tol, 10% -Tol, X5R, 15% TC,		C2I	1	06036A102KAT2A				
3		1uF, 0603			C2R, C5I	2				
			eramic 0.001uF 10V X7R 10% SME Ceramic Capacitor, 10 uF, 6.3 V, ± 1		C3I C3L	1	CC0603KRX7R6BB102 CL10A106KQ8NNNC			
			Ceramic Capacitor, 4.7 uF, 10 V, ± 1	0%, X5R, 0603 [1608 Metric]	C4U	1	CL10A475KP8NNNC			
			LED 0603 YELLOW S TVS DIODE 5V 15V SC		D1L D1U	1				
			Fuse PPTC SMD 06	03	F1P	1				3
			USB Connector Type C SN (Power pins joints = 12	pins)	J1C	1				
					J2C J3C	1				
			PMPB14XPZ		Q1P	1	PMPB14XPZ			
		Trans Gp Bjt NPN 25V 1.5A 300MW 3-PIN SOT-23 T/r Surface Mount Thick Film Chip Resistor 0603 Case 1.69K Ohms 1% Tolerance 100			Q1R, Q2R	2	SS8050-G			
		PPM		R0L	1	MCR03EZPFX1691				
4		SMD Chip Resistor, 5.1 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose Res Thick Film 0603 33K Ohm 1% 0.1W(1/10W) ±100ppm/C Pad SMD Automotive			R1C, R2C	2	CRCW06035K10FKEA			
		T/R SMD Chip Resistor, 100 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose		R1L	1	ERJ-3EKF3302V			4	
					R1P	1	AC0603FR-07100KL			
		SMD Chip Resistor, 10 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], T General Purpose			R1R, R1U, R2R, R2U, R3	3L, R3R, R4R 7	RC0603FR-0710KL			
		SMD Chip Resistor, 20 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose Res Thick Film 0603 2.49K Ohm 1% 1/10W ±100ppm/°C Molded SMD SMD Paper			R2L	1	CR0603-FX-2002ELF			
5		Res Thick Film	T/R		R4L	1	MCR03EZPFX2491			
			DGTL ISO 3750VRMS 4CH (LDO U-Reg Adj 0, 3A SO		U1I U1L	1				
		Single-Chip U	ISB to UART Bridge, 1024 Bytes El	EPROM, -40 to 85 degC, 28-pin	U1U	1				
		MM3Z12V	QFN, Tube ST1G Zener Diode, 12V 2% 200 m		ZD1P	1				5
	Semiconductor MM3Z12VST1G									
							Author:	CONFIDENTIAL		
6	Please consider LCSC (立创商城) as our first supplier				Title: = ProjectTitle		Approved:		20110 101	6
					Size: A3 Unit: mm Prj: =ProjectTitle			2-2024 Address Line 1	YOUR LOG HERE	()
	BOM FOR	REFERENC	E ONLY		Date: 06-12-2024 05:35 HMSheet 9 of 9		Variant: [No Varia SW version: 24.1	ations] Address Line 2 0.1.45 Address Line 3	- MERE	
	ALWAYS R	EFER TO T	HE LATEST EXCEL BOM	PROVIDED	Git Hash: 472 [No modification]		Address Line 4		~
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